Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

FAIRCHILD SEMICONDUCTOR®

June 2006

FDMJ1028N
N-Channel 2.5V Specified PowerTrench® MOSFET
20V, 3.2A, 90mΩ

Features

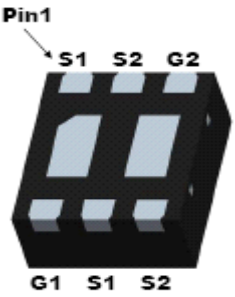
- Max $r_{DS(on)}$ = 90mΩ at V_{GS} = 4.5V
- Max $r_{DS(on)}$ = 130mΩ at V_{GS} = 2.5V
- Low gate charge
- High performance trench technology for extremely low $r_{DS(on)}$
- RoHS Compliant

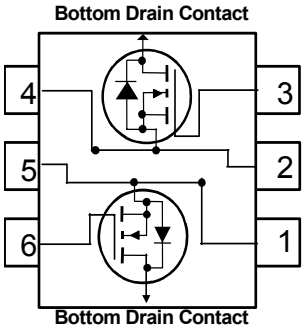
General Description

This dual N-Channel 2.5V specified MOSFET uses Fairchild's advanced low voltage PowerTrench process. The $r_{DS(on)}$ and thermal properties of the device are optimized for battery power management applications.

Applications

- Battery management
- Baseband Switches





MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DS}	Drain to Source Voltage		20	V
V_{GS}	Gate to Source Voltage		±12	V
I_D	Drain Current -Continuous		3.2	A
	-Pulsed		12	
P_D	Power Dissipation for Single Operation	(Note 1a)	1.4	W
		(Note 1b)	0.8	
T_J, T_{STG}	Operating and Storage Temperature		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance , Junction to Ambient	(Note 1a)	89	°C/W

Package Marking and Ordering Information

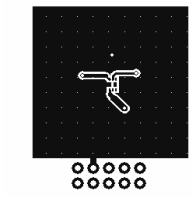
Device Marking	Device	Reel Size	Tape Width	Quantity
028	FDMJ1028N	7”	8mm	3000 units

Electrical Characteristics T_J = 25°C unless otherwise noted

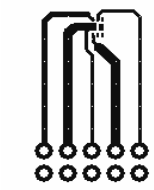
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 250μA, V_{GS} = 0V	20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250μA, referenced to 25°C		13		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 16, V_{GS} = 0V			1	μA
I_{GSS}	Gate to Source Leakage Current	V_{GS} = ±12V, V_{DS} = 0V			±100	nA
On Characteristics (Note 2)						
$V_{GS(th)}$	Gate to Source Threshold Voltage	V_{GS} = V_{DS}, I_D = 250μA	0.6	1.0	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250μA, referenced to 25°C		-3		mV/°C
$r_{DS(on)}$	Drain to Source On Resistance	V_{GS} = 4.5V, I_D = 3.2A		76	90	mΩ
		V_{GS} = 2.5V, I_D = 2.5A		106	130	
		V_{GS} = 4.5V, I_D = 3.2A, T_J =125°C		89	132	
g_{FS}	Forward Transconductance	V_{GS} = 5V, I_D = 3.2A		7.5		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} =10V, V_{GS} = 0V, f = 1MHz		200		pF
C_{oss}	Output Capacitance			50		pF
C_{rss}	Reverse Transfer Capacitance			30		pF
R_G	Gate Resistance	f = 1MHz		1		Ω
Switching Characteristics (Note 2)						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 10V, I_D = 1A V_{GS} = 4.5V, R_{GS} = 6Ω		7	14	ns
t_r	Rise Time			8	16	ns
$t_{d(off)}$	Turn-Off Delay Time			11	20	ns
t_f	Fall Time			2	4	ns
$Q_{g(tot)}$	Total Gate Charge at 10V	V_{DD} = 15V, V_{GS} = 3.2V, V_{GS} = 4.5V		2	3	nC
Q_{gs}	Gate to Source Gate Charge			0.4		nC
Q_{gd}	Gate to Drain Charge			1.0		nC
Drain-Source Diode Characteristics						
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0V, I_S = 1.16A		0.8	1.2	V
t_{rr}	Diode Reverse Recovery Time	I_F = 3.2A, dI_F/dt = 100A/μs		11		ns
Q_{rr}	Diode Reverse Recovery Charge			2.5		nC

Notes

1: $R_{\theta JA}$ is determined with the device mounted on a 1in^2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 89°C/W when mounted on a 1 in^2 pad of 2 oz copper



b. 156°C/W when mounted on a minimum pad of 2 oz copper

Scale 1 : 1 on letter size paper

2: Pulse Test: Pulse Width < 300θμs, Duty Cycle < 2.0%

Typical Characteristics T_J = 25°C unless otherwise noted

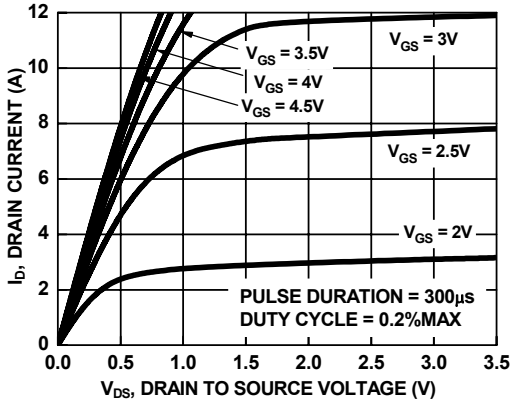


Figure 1. On Region Characteristics

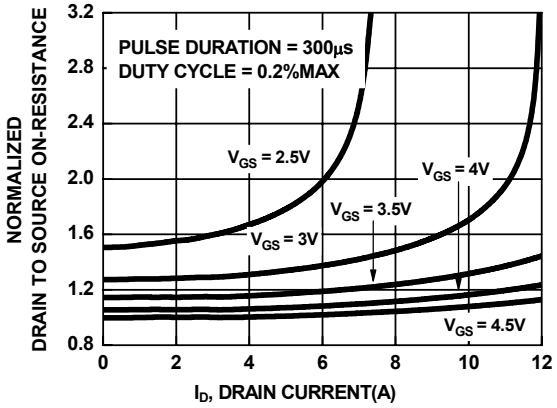


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

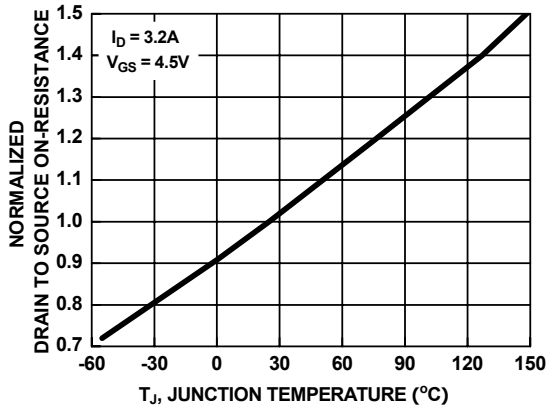


Figure 3. Normalized On Resistance vs Junction Temperature

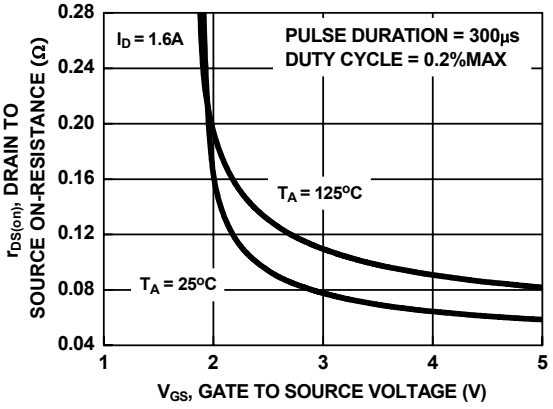


Figure 4. On-Resistance vs Gate to Source Voltage

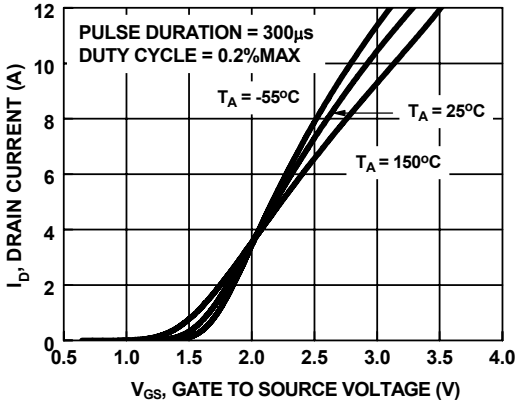


Figure 5. Transfer Characteristics

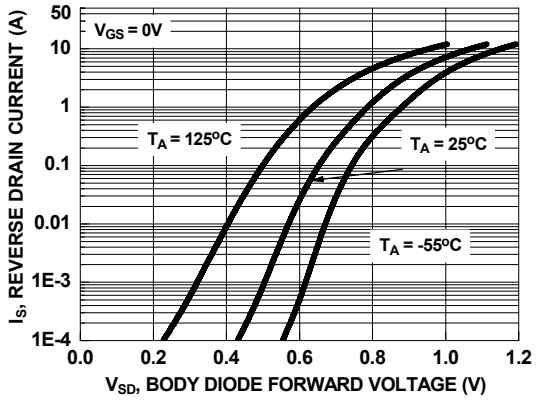


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

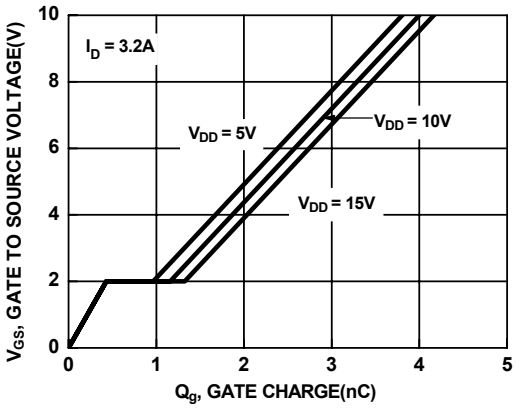


Figure 7. Gate Charge Characteristics

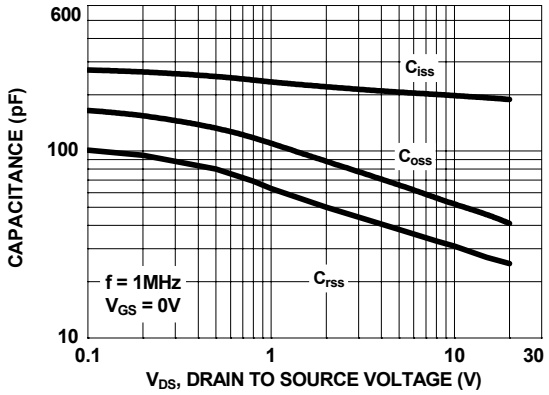


Figure 8. Capacitance vs Drain to Source Voltage

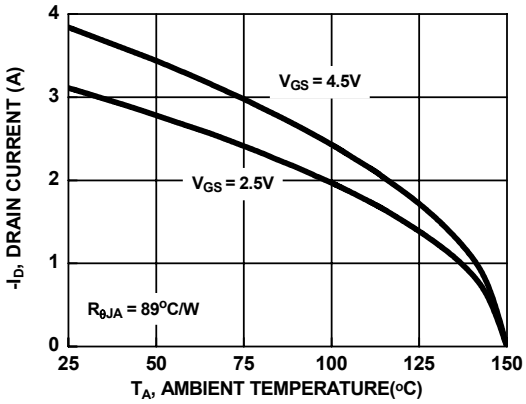


Figure 9. Maximum Continuous Drain Current vs Ambient Temperature

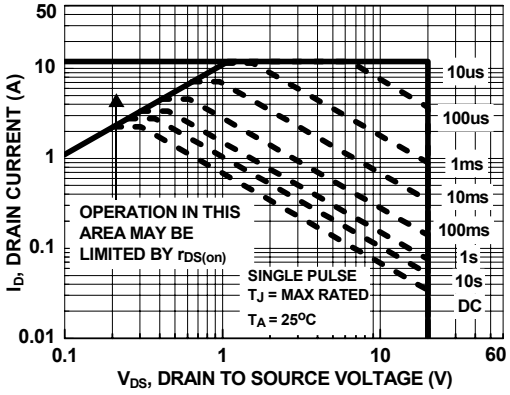


Figure 10. Forward Bias Safe Operating Area

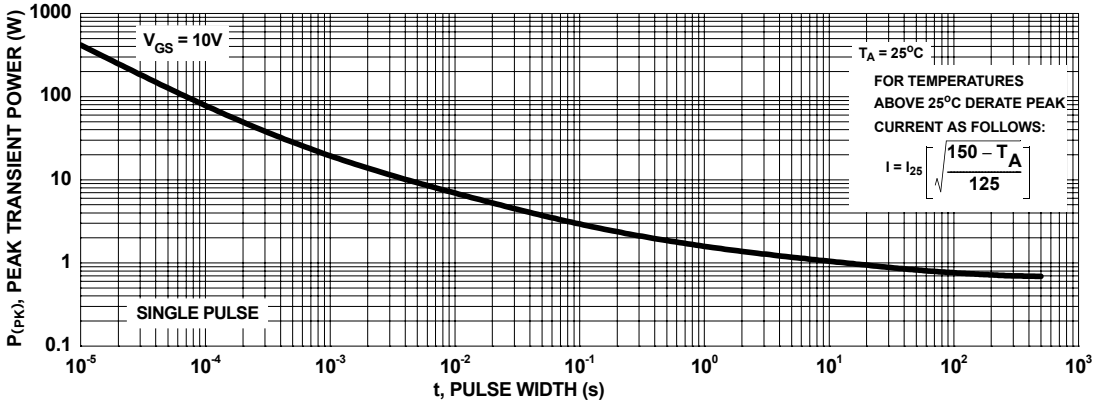


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25°C unless otherwise noted

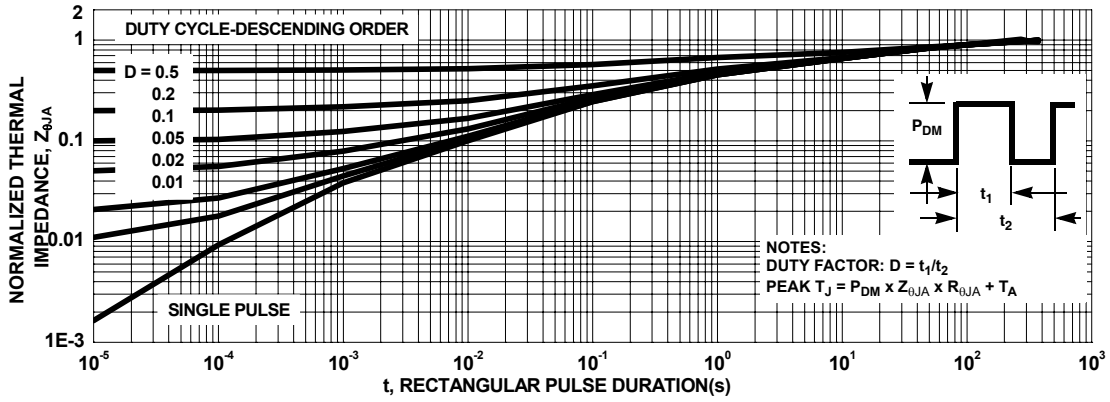
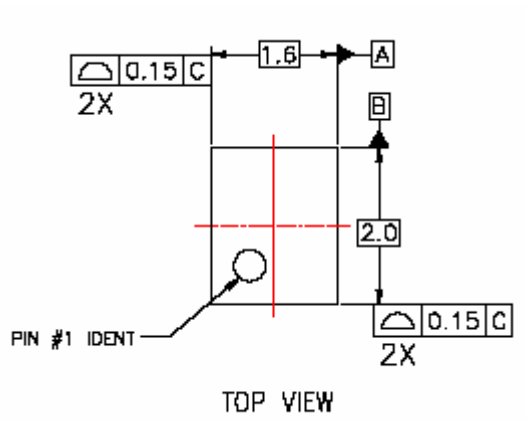
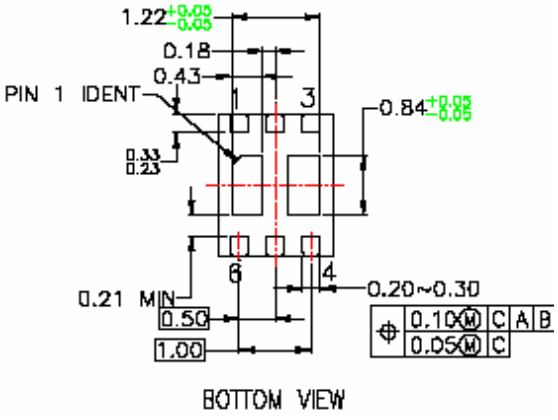
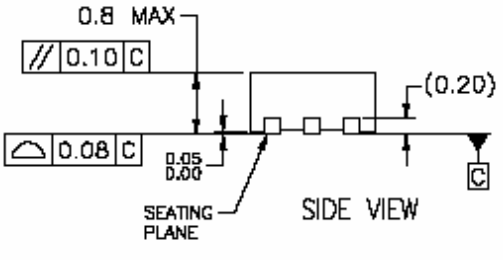


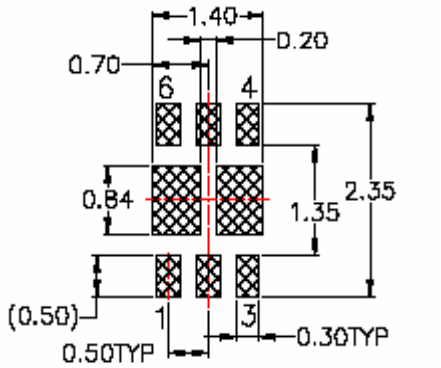
Figure 12. Transient Thermal Response Curve

Dimensional Outline and Pad Layout









RECOMMENDED LAND PATTERN

NOTES:

A. NON JEDEC REGISTRATION MOLDED PACKAGE OUTLINE,

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS AND TOLERANCES PER
ASME Y14.5M, 1994

MLP06Xrev1

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™	FAST®	ISOPLANAR™	PowerEdge™	SuperFET™
ActiveArray™	FASTr™	LittleFET™	PowerSaver™	SuperSOT™-3
Bottomless™	FPS™	MICROCOUPLER™	PowerTrench®	SuperSOT™-6
Build it Now™	FRFET™	MicroFET™	QFET®	SuperSOT™-8
CoolFET™	GlobalOptoisolator™	MicroPak™	QS™	SyncFET™
CROSSVOLT™	GTO™	MICROWIRE™	QT Optoelectronics™	TCM™
DOME™	HiSeC™	MSX™	Quiet Series™	TinyLogic®
EcoSPARK™	I^2C™	MSXPro™	RapidConfigure™	TINYOPTO™
E^2CMOS™	*i-Lo*™	OCX™	RapidConnect™	TruTranslation™
EnSigna™	ImpliedDisconnect™	OCXPro™	µSerDes™	UHC™
FACT™	IntelliMAX™	OPTOLOGIC®	ScalarPump™	UltraFET®
FACT Quiet Series™		OPTOPLANAR™	SILENT SWITCHER®	UniFET™
Across the board. Around the world.™		PACMAN™	SMART START™	VCX™
The Power Franchise®		POP™	SPM™	Wire™
Programmable Active Droop™		Power247™	Stealth™	

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

Rev. I19